

# PNP Transistor Bare Die – 2N6107

Rev 1.1 22/04/24

#### Bipolar Power Transistor in bare die form

Complement to NPN 2N6292

#### Features:

- Collector current up to 7A
- High DC Current Gain, h<sub>FE</sub> = 30-150 @ I<sub>C</sub> = 4A
- Low  $V_{CE(sat)} = 3.5V \text{ Max } @ I_C = 7A$
- Solderable back metal
- High Reliability tested grades for Military + Space

#### Ordering Information:

The following part suffixes apply:

- No suffix Commercial grade die
- "H" Hi-rel grade die + MIL-STD-38534 Class H LAT
- "K" Hi-rel grade die + MIL-STD-38534 Class K LAT.

LAT = Lot acceptance Test.

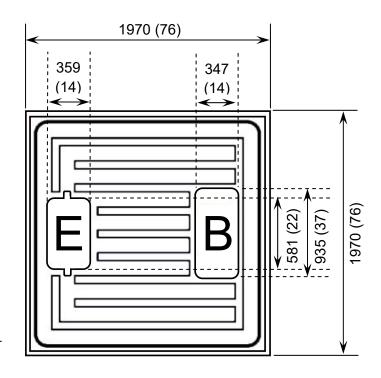
For information on Hi-Rel LAT flows please see below.

www.siliconsupplies.com\bare-die-lot-qualification

### **Supply Formats:**

- Default Die in Waffle Pack (100 per tray capacity)
- Sawn Wafer on Tape Specific request
- Unsawn Wafer Specific request
- With additional electrical selection Specific request
- Sawn as pairs or adjacent pair pick Specific request

### Die Dimensions in µm (mils)



**DIE BACK = COLLECTOR** 

### **Mechanical Specification**

1970 x 1970	µm	
76 x 76	mils	
359 x 581	µm	
14 x 22	mils	
347 x 935	μm	
14 x 37	mils	
250 (±25)	μm	
9.84 (±1)	mils	
Al		
Ti/Ni/Ag		
	76 x 76 359 x 581 14 x 22 347 x 935 14 x 37 250 (±25) 9.84 (±1) Al	





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## Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Collector-Base Voltage	V <sub>CBO</sub>	80	V
Collector-Emitter Voltage	V <sub>CEO</sub>	70	V
Emitter-Base Voltage	V <sub>EBO</sub>	5	V
Collector Current - Continuous	Ic	7	A
Base Current	I <sub>B</sub>	3	A
Operating Junction Temperature	TJ	-65 to 150	°C
Storage Temperature	T <sub>stg</sub>	-65 to 150	°C

#### Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS								
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	I <sub>E</sub> = 0	80	-	-	V		
Collector-Emitter Sustaining Voltage <sup>1</sup>	V <sub>CEO(SUS)</sub>	$I_B = 0, I_C = 100 \text{mA}$	70	-	-	V		
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	I <sub>C</sub> = 0	5	-	-	V		
Collector Cut-off Current	I <sub>CEO</sub>	$V_{CE} = 60V, I_{B} = 0$	-	-	1.0	mA		
	I <sub>CEX</sub>	V <sub>CE</sub> = 80V, V <sub>BE(off)</sub> = 1.5V	-	-	0.1	mA		
	I <sub>CEX</sub> <sup>2</sup>	V <sub>CE</sub> =70V,V <sub>BE(off)</sub> =1.5V,T <sub>J</sub> = 125°C	-	-	2.0	mA		
Emitter Cut-off Current	I <sub>EBO</sub>	V <sub>EB</sub> = 5V, I <sub>C</sub> = 0	-	-	1.0	mA		
ON CHARACTERISTICS								
Forward-Current Transfer Ratio <sup>1</sup>	h <sub>FE</sub>	$I_{C} = 2A, V_{CE} = 4V$	30	-	150	-		
	TIFE	$I_{C} = 7A, V_{CE} = 4V$	2.3	-	-	-		
Collector-Emitter Saturation Voltage <sup>1</sup>	V <sub>CE(sat)</sub>	I <sub>C</sub> = 7A, I <sub>B</sub> = 3A	-	-	3.5	V		
Base-Emitter On Voltage <sup>1</sup>	V <sub>BE(on)</sub>	$I_{C} = 7A, V_{CE} = 4V$	-	-	3.0	V		
SMALL SIGNAL CHARACTERISTICS <sup>2</sup>								
Transition Frequency <sup>3</sup>	f <sub>T</sub>	$V_{CE} = 4V, I_{C} = 0.5A, f = 1MHz$	10	-	-	MHz		
Small-Signal Current Gain	h <sub>fe</sub>	$V_{CE} = 4V$ , $I_{C} = 0.5A$ , $f = 50kHz$	20	-	-	-		

<sup>1.</sup> Pulsed duration = 300µs, duty cycle ≤ 2%

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<sup>2.</sup> Not production testing in die form, characterized by chip design and package verification

<sup>3.</sup>  $f_T = |h_{fe}| \circ f_{TEST}$